



十速科技股份有限公司
tenx technology inc.

**Advance
Information**

TM58RC10

User Manual

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1. Feature

- ROM: 1K x 14 bits
- RAM: 25 x 8 bits
- STACK: 2 Levels
- Two operation modes: General mode and Advanced mode
- Four external Oscillate modes: RC, LP Crystal, NT Crystal and HS Crystal
- I/O ports: 12/13 I/O PAD
- 8 Pull High I/O PAD from Port-B (PULL-Hi resistor = 54K (Vdd = 5V))
- 4 normal I/O PAD from Port PA3~A0
- 1 special Input PAD from EXT_CLK/PA4
- Wake-up: Port B pin-change wake-up (Advanced mode only)
- Timer/counter: 8bits x1 (TMR0)
- Prescaler: 3 Bits
- Watchdog Timer: On chip WDT is based on internal RC oscillator. The shortest period is 20mS; user can extend the WDT overflow period to 2.56S by using prescaler.
- Power-On Reset
- Reset Timer: 20 mS (5V)
- Reset mode: (a). Power-On reset
 - (b). Low voltage reset
 - (c). 1 External Pin reset (RESETB)
 - (d). Watchdog timer count overflow reset
- Operation Voltage: 2.2V~5.5V
- Instruction set: 78
- Reset vector: 3FFH
- Package Type: (a). TM58RC10SS20C
 - (b). TM58RC10D18C
 - (c). TM58RC10S18C
 - (d). TM58RC10D14C
 - (e). TM58RC10S14C

2. Pin Definition & Pad Assignment

(1). 18 Pin & 20 Pin

PA2	1		18	PA1
PA3	2		17	PA0
EXT_CLK/PA4	3		16	OSC1
RESETB	4		15	OSC2
VSS	5		14	VDD
PB0	6		13	PB7
PB1	7		12	PB6
PB2	8		11	PB5
PB3	9		10	PB4

18 Pin Package Types: DIP (TM58RC10D18C)
 SOP (TM58RC10S18C)

PA2	1		20	PA1
PA3	2		19	PA0
EXT_CLK/PA4	3		18	OSC1
RESETB	4		17	OSC2
VSS	5		16	VDD
VSS	6		15	VDD
PB0	7		14	PB7
PB1	8		13	PB6
PB2	9		12	PB5
PB3	10		11	PB4

20Pin Package Type: SSOP (TM58RC10SS20C)

(2). 14Pin

EXT_CLK/PA4	1		14	OSC1
RESETB	2		13	OSC2
VSS	3		12	VDD
PB0	4		11	PB7
PB1	5		10	PB6
PB2	6		9	PB5
PB3	7		8	PB4

14 Pin Package Type: DIP (TM58RC10D14C)
 SOP (TM58RC10S14C)

3. PIN Description

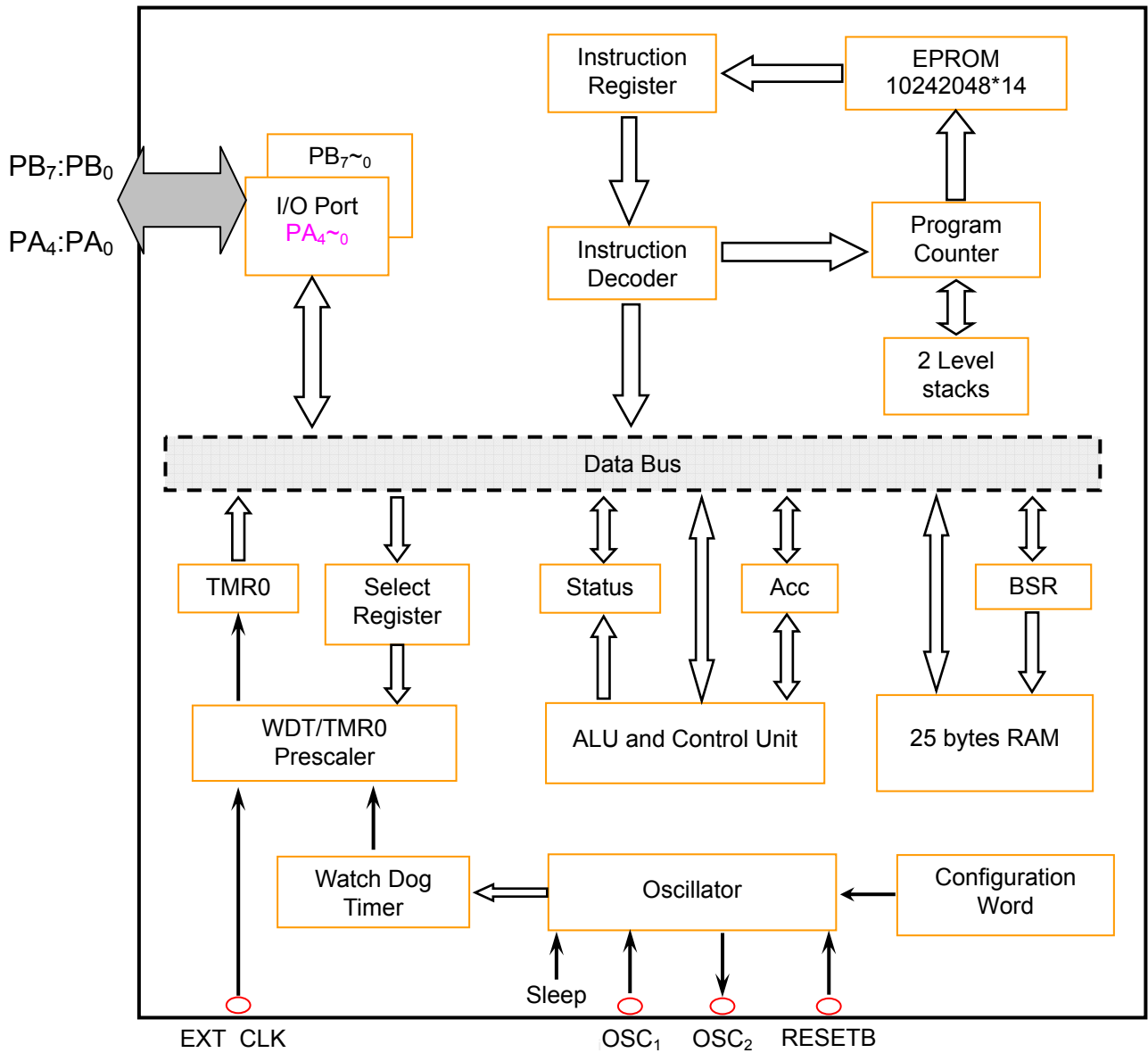
Pin name	I/O	Description
EXT_CLK/PA4	I	1. External clock input to TMR0 counter 2. PA4 input (When config bit7=1)
PA3-0	I/O	I/O port
PB7-0	I/O	1. I/O port 2. Pin-change wake-up (Advanced mode only) 3. Pull-UP (Advanced mode only)
RESETB	I	System reset signal
OSC1	I	Oscillator input
OSC2	O	Oscillator output
VDD	P	Power input
VSS	P	Ground input

I: Input; O: Output; I/O: Bi-direction; P: Power

4. Control Register

Name	Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CONFIG (Instruction)		RTCEN	TYPE	LV1	LV0	CPT	WDTE	FOSC1	FOSC0
SELECT				SUR0	EDGE0	PSA	PS2	PS1	PS0
IAR	\$00				A4	A3	A2	A1	A0
TMR0	\$01	D7	D6	D5	D4	D3	D2	D1	D0
PC	\$02	D7	D6	D5	D4	D3	D2	D1	D0
STATUS	\$03			SA0	\overline{TO}	\overline{PD}	Z	DC	C
BSR	\$04				D4	D3	D2	D1	D0
I/O PortA	\$05				PA4	PA3	PA2	PA1	PA0
I/O PortB	\$06	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0

5. System Block Diagram



6. Memory Map

TM58RC10 memory is organized into program memory and data memory.

6-1. Program memory

TM58RC10 allow directly goto any address in 1K memories without limited by page size. In addition, lcall and lgoto instructions are employed to provide flexible addressing mode. TM58RC10 has a 10-bits program counter capable of accessing 1K spaces. If accessing address has over 1K, then the address will map to physical 1K memories, i.e. 1K+M will be mapped to M. A NOP at the reset vector location will cause a restart at address 000h. A simple map to induce illustrate ROM organization is shown in figures 6-1.

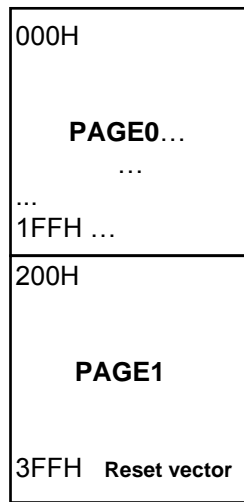


Figure 6-1 The ROM Organization

The configuration word is located 800H that contains OSC selection, WDT enable and code protection. (Figure 6-2).

Bit	Symbol	Description			
1~0	FOSC1~FOSC0	Bit1	Bit0	OSC Type	Resonance Frequency
		0	0	LP (low speed)	32~200K Hz
		0	1	NT (Normal speed)	200K~10M Hz
		1	0	HS (high speed)	10~20M Hz
		1	1	RC	32K ~ 6 M Hz
2	WDTE	WDTE: Watchdog enable/disable control 1: WDT enable 0: WDT disable			
3	CPT	CPT: Code Protection bit 1: OFF 0: ON			
5~4	LV1~LV0	LV1	LV0	Detect voltage	
		0	0	4V	
		0	1	Unimplemented	
		1	0	2.3V	
		1	1	Don't use	
6	TYPE	TYPE: Select operating mode 1: Advanced mode (PB pin-change wakeup) 0: General mode			
7	RTCEN	1		PA4 input	
		0		Timer input only	

Figure 6-2 The Configuration Word

6-2. Data memory

Data memory is composed of special register and general-purpose ram. TM58RC10 has 25 general-purpose registers that accessed by using direct or indirect addressing. The special function registers include the program counter (PC), the timer (TMR0) register, the status register, the bank select register, and the I/O port registers. Furthermore, TM58RC10 has 3 auxiliary registers that include indirect addressing register (IAR), the select register (Select) and the I/O direction register (IODIR). The register map is shown in *figure 6-3*.

	Bank0
00h	IAR
01h	TMR0
02h	PC
03h	STATUS
04h	BSR
05h	PORTA
06h	PORTB
9+16=25	General Purpose Register 07 – 0F
	General Purpose Register 10 -1F

Figure 6-3 The Register Map

The IAR (indirect addressing register) is not a physical register and is used to assist BSR with indirect addressing. Any instruction attempts to access IAR actually mapping to another address that is pointed by BSR. Since IAR is not a material circuit, user reads IAR itself (BSR=00H) will always return 00h at data bus. Writing to IAR itself will like NOP.

Select register is used to control WDT and TMR0. It has not assigned a specific address in data memory and can only set control bits by “select” instruction, i.e. it is write-only register. The context of accumulator will be sent to the select register by executing the “select” instruction. If select register has never set by program, its default value is 3FH. We drew *Figure 6-4* to explain how to set select register.

Bit	Symbol	Description				
		PS2	PS1	PS0	TMR0 rate	WDT rate
2~0	PS2~PS0	0	0	0	1:2	1:1
		0	0	1	1:4	1:2
		0	1	0	1:8	1:4
		0	1	1	1:16	1:8
		1	0	0	1:32	1:16
		1	0	1	1:64	1:32
		1	1	0	1:128	1:64
		1	1	1	1:256	1:128
3	PSA	PSA: Prescaler assignment bit 1: Prescaler assigned to WDT 0: Prescaler assigned to TMR0				
4	EDGE0	EDGE0: TMR0 source signal edge control bit 1: increment when H→L transition on external clock 0: increment when L→H transition on external clock				
5	SUR0	SUR0: TMR0 clock source bit 1: EXT_CLK clock input 0: (System clock)/4 or internal instruction cycle				

Figure 6-4 Select Register

The I/O Direction control register is similar to the Select register that is write-only register. To set an I/O port pin as input, the corresponding direction control bit must be high. Similarly, the zero represents output. Any direction control bit can be programmed individually as input or output by using IODIR instruction. If the register is not programmed, than all I/O ports always keep input mode.

PC (program counter) is a 10-bit wide binary counter and increases itself for every instruction cycle, except the following conditions.

- (1). call, goto, lgoto and lcall: the label will move to PC
- (2). retla and ret: the top value of stack will pop to PC

Incrementing PC when it changes to the next higher page. It should be noted that the page select bits in the status register would not be changed synchronously. The following Goto, Call, or MOVAM 02H will return to the previous page, unless the page select bits have been updated in program. In order to reduce the complexity of programming, TM58RC10 provides 2 instructions to facilitate subroutine call and branch handling which are LCALL and LGOTO. LCALL and LGOTO can address to anywhere in the ROM, but the page select bits are unnecessary. The attached operands of CALL and GOTO are 8-bit and 9-bit respectively, and so need extra bits (page select bits) to address whole memory. However, LCALL and LGOTO have 10-bit wide operands that are easy to address the total ROM space.

TMR0 is 8-bit wide binary counter/timer. This register increases by an external signal edge applied to EXT_CLK pin, or by internal instruction cycle. It has the following features.

- (1). Readable and writeable
- (2). Synchronize with 2 internal clocks
- (3). Can use programmable prescaler by setting select register

The other details will be described in follow-up chapter.

Status register contains page select bits, time out bit, power down bit and the status of ALU. Please note that \overline{TO} and \overline{PD} are controlled by hardware and unchangeable by program.

Bit	Symbol	Description	
0	C	Carry and \overline{Borrow} bit:	
		ADD instruction	SUB instruction
		1: a carry occurred from the MSB 0: no carry	1: no borrow (Note1) 0: a borrow occurred from the MSB
1	DC	Nibble Carry and Nibble \overline{Borrow} bit	
		ADD instruction	SUB instruction
		1: a carry from the low nibble bits of the result occurred 0: no carry	1: no borrow 0: a borrow from the low nibble bits of the result occurred
2	Z	Zero bit: 1: the result of a logic operation is zero 0: the result of a logic operation is not zero	
3	\overline{PD}	Power down flag bit: (Note2) 1: after power-on or by the CLRWDT instruction 0: execute SLEEP instruction	
4	\overline{TO}	Time out flag bit: 1: after power-on or by the CLRWDT or SLEEP instruction 0: Occur WDT time-overflow	
5	SA0		Page Location
		0	Page0 (000H~1FFH)
	1	Page1 (200H~3FFH)	

Figure 6-5 Status Register

Note1: A SUB instruction is executed by adding the 2's complement of the subtrahend, so C = 1 represents positive result. The Figure 6-5-1 show the relation between C-bit and borrow.

B0H – 50H										50H – B0H									
	C	B7	B6	B5	B4	B3	B2	B1	B0		C	B7	B6	B5	B4	B3	B2	B1	B0
+		1	0	1	1	0	0	0	0	+		0	1	0	1	0	0	0	0
=	1	0	1	1	0	0	0	0	0	=	0	1	0	1	0	0	0	0	0

Figure 6-5-1

Note2: The \overline{TO} and \overline{PD} bits are active low that can be used to determine different causes of reset. The Figure 6-5-2 illustrates the value of \overline{TO} and \overline{PD} after the relative reset events.

\overline{TO}	\overline{PD}	Reset Event
0	0	WDT time out from sleep mode
0	1	WDT time out from normal mode
1	0	Input a “Low” at RESETB from sleep mode
1	1	Power on reset
Unchanged	Unchanged	Input a “Low” at RESETB from normal

Figure 6-5-2

BSR (bank select register) is associated with IAR to indirectly access the data memory. The BSR<4:0> bits are used to select data memory addresses 00h to 1Fh (Bank0). The addressing map is shown in Figure 6-6.

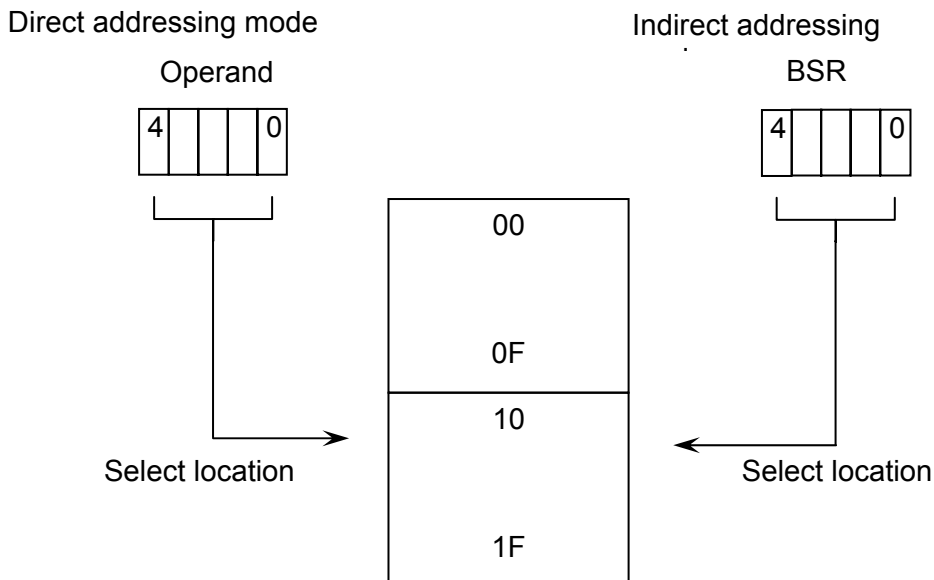


Figure 6-6 The Direct and Indirect Addressing Map

Port A~B are programmable I/O ports. Please note that read I/O instruction always read the I/O pin even though the pin is output mode. On reset, all I/O pins were set as input mode until IODIR has been changed.

7. Functional Description

7-1. TMR0 and Watchdog timer

Figure 7-1 shows the block diagram of the TMR0/WDT prescaler. As shown in the figure, the prescaler register can be a prescaler for TMR0 or be a postscaler for WDT.

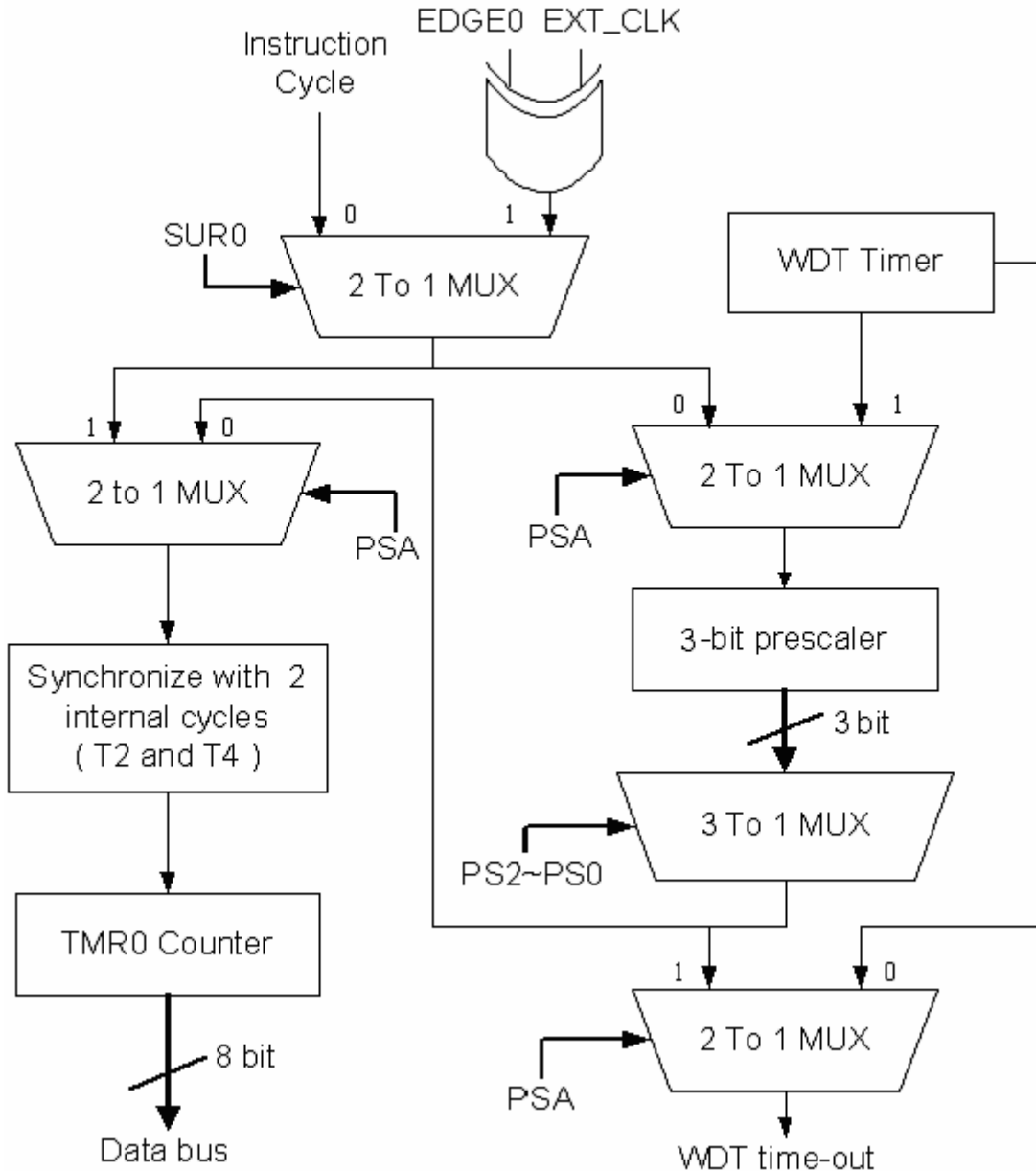


Figure 7-1 Block Diagram of the TMR0/WDT Prescaler

The TMR0 is an 8-bit timer/counter. The clock source of TMR0 can come from the instruction clock or the external clock.

To select the instruction clock, the SUR0 bit of the select register should be clear. When no prescaler is used, TMR0 will increase by 1 at every instruction cycle.

To select the external clock, the SUR0 bit of the select register should be set. In this mode, TMR0 relies on the EDGE0 bit to determine that TMR0 is increased by 1 at every falling or rising edge. When an external clock is used for TMR0, a problem must be noted that the external clock synchronizes with internal clock. TM58RC10 synchronizes external clock by sampling internal clock at T2 and T4. If external pulse is smaller than 2 internal cycles, the pulse maybe ignored. Therefore, the external clock must keep stable state (high or low) for at least 2 internal cycles.

The WDT counter is an 8-bit binary counter. The clock source of WDT is provided by an independent on-chip RC oscillator that does not need any external clock. Therefore, the WDT will keep counting even if the chip has slept already. A WDT time-out will restart system and set the time-out flag bit (bit4 of status register) as “0”. The WDT time-out period vary with temperature, power voltage and process. This period can be improved via the prescaler. The maximum division ratio can up to 1:128 by setting PS2~PS0 as “111”.

The prescaler can be assigned to either the TMR0 or the WDT via the PSA bit. Note that either WDT or TMR0 can employ the prescaler simultaneously. The following Example (1-2) must be executed when changing PSA from TMR0 to the WDT and from WDT to the TMR0 respectively. These examples can avoid an unintended time-out reset.

When the prescaler is assigned to WDT, “CLRWDT” and “SLEEP” instruction will clear the prescaler and the WDT. When the prescaler is assigned to TMR0, the prescaler will be cleared by any instruction that writes to TMR0.

```

Clrwdt
Clrm   TMR0       ; clear prescaler & TMR0
Movla  B'00xx1111'
Select
Clrwdt
Movla  B'00xx1xxx';set prescaler to desired
Select                ; WDT rate
    
```

Example 1
Changing prescaler from TMR0 to WDT to WDT

```

Clrwdt ; clear prescaler & WDT
Movla  B'00xx0xxx'
Select ; set prescaler to TMR0
          ; with new rate
    
```

Example 2
Changing prescaler from WDT to TMR0

7-2. Reset

TM58RC10 may be reset by one of the following conditions:

- (1). Power-on.
- (2). RESETB/VPP pin input a negative pulse.
- (3). WDT timer out reset (if enable WDTE).
- (4). Low Voltage reset.

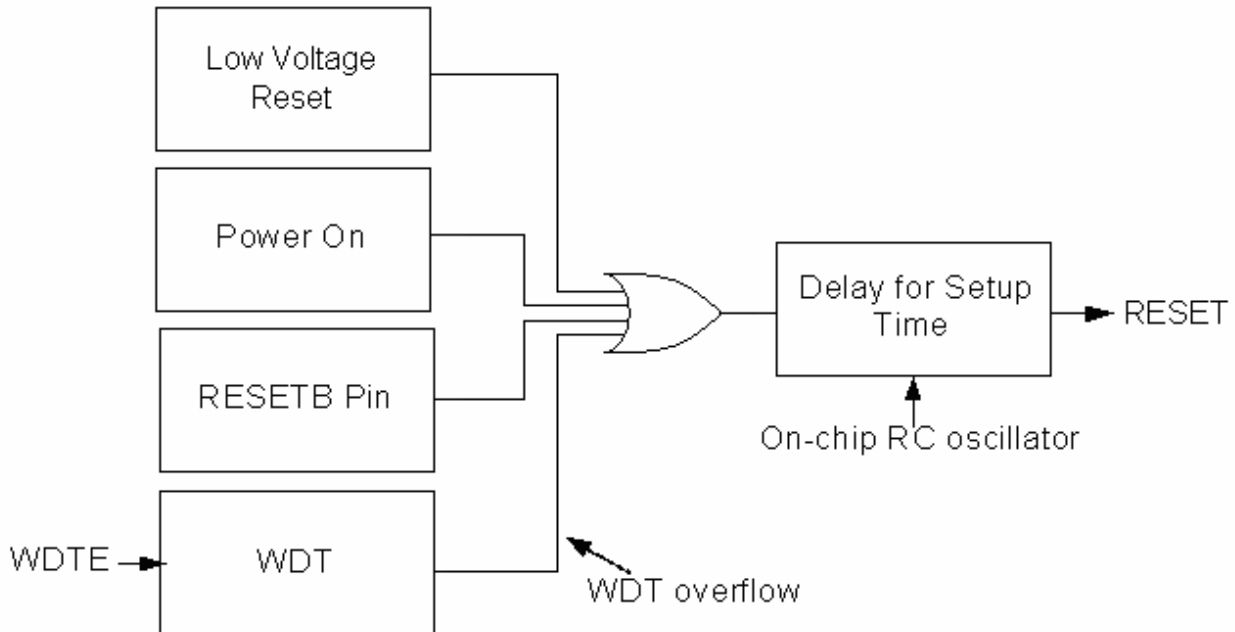


Figure 7-2 Scheme of the Reset Controller

As shown in the *figure7-2*, four reset conditions are listed. In general, we call the first and second reset-case as cold reset. The cold reset time may be too short for slow crystals and RC oscillators that require much longer than setup time (note) to oscillate.

Note: The setup time is approximately 20ms that will affect due to power voltage, process and temperature variations.

The last two cases are called warm reset. The different reset events will affect registers and ram. The \overline{TO} and \overline{PD} bits can be used to determine the type of reset. These relations are listed in *figure 7-3*.

Address	Name	Cold Reset	Warm Reset
N/A	Accumulator	xxxx xxxx	pppp pppp
N/A	IODIR	1111 1111	1111 1111
N/A	Select	--11 1111	--11 1111
00h	IAR	---- ----	---- ----

Address	Name	Cold Reset	Warm Reset
01h	TMR0	xxxx xxxx	pppp pppp
02h	PC	111 1111 1111	111 1111 1111
03h	STATUS	0001 1xxx	000? ?ppp
04h	BSR	111x xxxx	111p pppp
05h	PORTA	000x xxxx	000p pppp
06h	PORTB	xxxx xxxx	pppp pppp
	General Purpose RAM	xxxx xxxx	pppp pppp

7-3. RESET CONDITIONS

X: unknown; P: previous data; ?: value depends on condition; -:unimplemented and read as “0”.

7-4. Advanced Mode

In advanced mode, we provide PB7~0 pull-up, PB7~0 wake up functions and PA4 input. If (TYPE=1) and only if (Port-B Bit [N] as input pin); then Port-B Bit [N] will PULL-Hi and enable wake-up function. ([N] =7~0)

In advanced mode, we provide wake up function. Chip can be wake up from Sleep mode when the logic of the input pin of the Port-B is changed. So we need to read the logic of the input pin before sleep. In advanced mode, the use of a pull-up resistor for the input pin of Port-B. You can set the I/O direction of Port-B by “IODIR” instruction. If the chip wakes up from sleep state, the next instruction of SLEEP will be executed.

Example-1: Wake up

```

Movla    0fh
Iodir    06h        ;; set i/o direction of PORTB
.....
Movm     06h,a      ;; read the voltage of the input pin before sleep
sleep    ;; only port-B 3、2、1、0 cab be wakeup
call     delay20ms  ;;this instruction will be executed after wake up
    
```

The debouche time is the interval that must pass before a second pressing of a key is accepted. User can set this interval with the delay routine (Refer to the Example-1.).

Example 2: Key_Debounce

```
After_wakeup
;-----
int_nt1          ;; filter out key begin bounce
  btmsc rb,0
  lgoto int_nt1
int_loop1       ;; filter out key end bounce
  call delay    ;; worse case 30ms
  btms rb,0
  lgoto int_loop1

  call delay_routine ;; such as 30ms
  btms rb,0
  lgoto int_loop1
;-----
```

8. Instruction Set

Mnemonic Operands	Instruction Code (Advance)	Cycles	Status Affected	OP-code
ADDAM M, m	$(M)+(\text{acc}) \rightarrow (M)$	1	C, DC, Z	10 0101 1MMM MMMM
ADDAM M, a	$(M)+(\text{acc}) \rightarrow (\text{acc})$	1	C, DC, Z	10 0101 0MMM MMMM
ANDAM M, m	$(M) \cdot (\text{acc}) \rightarrow (M)$	1	Z	10 0100 1MMM MMMM
ANDAM M, a	$(M) \cdot (\text{acc}) \rightarrow (\text{acc})$	1	Z	10 0100 0MMM MMMM
ANDLA I	Literal $\cdot (\text{acc}) \rightarrow (\text{acc})$	1	Z	11 1001 iiiiiiii
BCM M, b0	Clear bit0 of (M)	1	None	00 1100 0MMM MMMM
BCM M, b1	Clear bit1 of (M)	1	None	00 1100 1MMM MMMM
BCM M, b2	Clear bit2 of (M)	1	None	00 1101 0MMM MMMM
BCM M, b3	Clear bit3 of (M)	1	None	00 1101 1MMM MMMM
BCM M, b4	Clear bit4 of (M)	1	None	00 1110 0MMM MMMM
BCM M, b5	Clear bit5 of (M)	1	None	00 1110 1MMM MMMM
BCM M, b6	Clear bit6 of (M)	1	None	00 1111 0MMM MMMM
BCM M, b7	Clear bit7 of (M)	1	None	00 1111 1MMM MMMM
BSM M, b0	Set bit0 of (M)	1	None	00 1000 0MMM MMMM
BSM M, b1	Set bit1 of (M)	1	None	00 1000 1MMM MMMM
BSM M, b2	Set bit2 of (M)	1	None	00 1001 0MMM MMMM
BSM M, b3	Set bit3 of (M)	1	None	00 1001 1MMM MMMM
BSM M, b4	Set bit4 of (M)	1	None	00 1010 0MMM MMMM
BSM M, b5	Set bit5 of (M)	1	None	00 1010 1MMM MMMM
BSM M, b6	Set bit6 of (M)	1	None	00 1011 0MMM MMMM
BSM M, b7	Set bit7 of (M)	1	None	00 1011 1MMM MMMM
BTMSC M, b0	If bit0 of (M) = 0, skip next instruction	1 + (skip)	None	00 0100 0MMM MMMM
BTMSC M, b1	If bit1 of (M) = 0, skip next instruction	1 + (skip)	None	00 0100 1MMM MMMM
BTMSC M, b2	If bit2 of (M) = 0, skip next instruction	1 + (skip)	None	00 0101 0MMM MMMM
BTMSC M, b3	If bit3 of (M) = 0, skip next instruction	1 + (skip)	None	00 0101 1MMM MMMM
BTMSC M, b4	If bit4 of (M) = 0, skip next instruction	1 + (skip)	None	00 0110 0MMM MMMM
BTMSC M, b5	If bit5 of (M) = 0, skip next instruction	1 + (skip)	None	00 0110 1MMM MMMM
BTMSC M, b6	If bit6 of (M) = 0, skip next instruction	1 + (skip)	None	00 0111 0MMM MMMM
BTMSC M, b7	If bit7 of (M) = 0, skip next instruction	1 + (skip)	None	00 0111 1MMM MMMM

Mnemonic Operands	Instruction Code (Advance)	Cycles	Status Affected	OP-code
BTMSS M, b0	If bit0 of (M) = 1, skip next instruction	1 + (skip)	None	00 0000 0MMM MMMM
BTMSS M, b1	If bit1 of (M) = 1, skip next instruction	1 + (skip)	None	00 0000 1MMM MMMM
BTMSS M, b2	If bit2 of (M) = 1, skip next instruction	1 + (skip)	None	00 0001 0MMM MMMM
BTMSS M, b3	If bit3 of (M) = 1, skip next instruction	1 + (skip)	None	00 0001 1MMM MMMM
BTMSS M, b4	If bit4 of (M) = 1, skip next instruction	1 + (skip)	None	00 0010 0MMM MMMM
BTMSS M, b5	If bit5 of (M) = 1, skip next instruction	1 + (skip)	None	00 0010 1MMM MMMM
BTMSS M, b6	If bit6 of (M) = 1, skip next instruction	1 + (skip)	None	00 0011 0MMM MMMM
BTMSS M, b7	If bit7 of (M) = 1, skip next instruction	1 + (skip)	None	00 0011 1MMM MMMM
CALL I	Call subroutine	2	None	11 0110 iii iiiii
CLRA	Clear accumulator	1	Z	10 0001 0000 0000
CLRM M	Clear memory M	1	Z	10 0001 1MMM MMMM
CLRWDT	Clear watch-dog register	1	TO, PO	10 0000 0000 0001
COMM M, m	$\sim(M) \rightarrow (M)$	1	Z	10 0010 1MMM MMMM
COMM M, a	$\sim(M) \rightarrow (\text{acc})$	1	Z	10 0010 0MMM MMMM
DECM M, m	Decrement M to M	1	Z	10 0110 1MMM MMMM
DECM M, a	$(M) - 1 \rightarrow (\text{acc})$	1	Z	10 0110 0MMM MMMM
DECMSZ M, m	$(M) - 1 \rightarrow (M)$, skip if (M) = 0	1 + (skip)	None	10 0111 1MMM MMMM
DECMSZ M, a	$(M) - 1 \rightarrow (\text{acc})$, skip if (M) = 0	1 + (skip)	None	10 0111 0MMM MMMM
GOTO I	Goto branch	2	None	11 101i iiiiiiii
INCM M, m	$(M) + 1 \rightarrow (M)$	1	Z	10 1000 1MMM MMMM
INCM M, a	$(M) + 1 \rightarrow (\text{acc})$	1	Z	10 1000 0MMM MMMM
INCMSZ M, m	$(M) + 1 \rightarrow (M)$, skip if (M) = 0	1 + (skip)	None	10 1001 1MMM MMMM
INCMSZ M, a	$(M) + 1 \rightarrow (\text{acc})$, skip if (M) = 0	1 + (skip)	None	10 1001 0MMM MMMM
IODIR M	Set i/o direction	1	None	10 0000 0000 0MMM
IORAM M, m	(M) ior (acc) \rightarrow (M)	1	Z	10 1111 1MMM MMMM
IORAM M, a	(M) ior (acc) \rightarrow (acc)	1	Z	10 1111 0MMM MMMM
IORLA I	Literal ior (acc) \rightarrow (acc)	1	Z	11 0011 iiiiiiii

Mnemonic Operands	Instruction Code (Advance)	Cycles	Status Affected	OP-code
LCALL I	Call subroutine. However, LCALL can addressing 1K address	2	None	01 0iii iiiiiiii
LGOTO I	Go branch to any address	2	None	01 1iii iiiiiiii
MOVAM m	Move data from acc to memory	1	None	10 0000 1MMM MMMM
MOVLA I	Move literal to accumulator	1	None	11 0001 iiiiiiii
MOVMM, m	(M) → (M)	1	Z	10 0011 1MMM MMMM
MOVMM, a	(M) → (acc)	1	Z	10 0011 0MMM MMMM
NOP	No operation	1	None	10 0000 0000 0000
RET	Return	2	None	11 1111 0111 1111
RETLA I	Return and move literal to accumulator	2	None	11 1100 iiiiiiii
RLM M, m	Rotate left from m to itself	1	C	10 1100 1MMM MMMM
RLM M, a	Rotate left from m to acc	1	C	10 1100 0MMM MMMM
RRM M, m	Rotate right from m to itself	1	C	10 1110 1MMM MMMM
RRM M, a	Rotate right from m to acc	1	C	10 1110 0MMM MMMM
SELECT	Set select register	1	None	10 0000 0000 0010
SLEEP	Enter sleep (saving) mode	1	TO, PO	10 0000 0000 0011
SUBAM M, m	(M)–(acc) → (M)	1	C, DC, Z	10 1010 1MMM MMMM
SUBAM M, a	(M)–(acc) → (acc)	1	C, DC, Z	10 1010 0MMM MMMM
SWAPM M, m	Swap data from m to itself	1	None	10 1101 1MMM MMMM
SWAPM M, a	Swap data from m to acc	1	None	10 1101 0MMM MMMM
XORAM M, m	(M) xor (acc) → (M)	1	Z	10 1011 1MMM MMMM
XORAM M, a	(M) xor (acc) → (acc)	1	Z	10 1011 0MMM MMMM
XORLA I	Literal xor (acc) → (acc)	1	Z	11 1000 iiiiiiii

9. Electrical Characteristics

9-1. Absolute Maximum Ratings

Supply Voltage Vss-0.3V to Vss+5.5V Storage Temperature -50°C to 125°C
 Input Voltage Vss-0.3V to VDD+0.3V Operating Temperature 0°C to 70°C

9-2. DC Characteristics

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		VDD	Conditions				
VDD	Operating Voltage	---		2.2		5.5	V
VDVT	Detect Voltage	5V	Low Voltage Detector (I _{dd} = 3uA) Config bit6.bit5=00		4		V
		3V	Low Voltage Detector (I _{dd} = 1.5uA) Config bit6.bit5=10		2.3		V
VIL	Input Low Voltage	5V	I/O Port			0.8	V
IDD1	Standby Current	5V	WDT disable		1		uA
			WDT enable		10		
IIL	Input Leakage Current	5V	V _{in} =VDD, VSS		1		uA
IDD1	Standby Current	5V	LVD disable,WDT disable,LV disable		1		uA
			LVD disable,WDT enable,LV disable		5		uA
			LVD disable,WDT disable,LV disable		1		uA
			LVD disable,WDT enable,LV disable		2		uA
IIL	Input Leakage Current	5V	V _{in} =VDD, VSS		1		uA
			V _{ol} =01V		35		
			V _{ol} =1.5V		50		
RPUHI	Pull_Hi Pin Resister	5V	Set PortB input pin and Pull_Hi		60		KΩ
		3V	Set PortB input pin and Pull_Hi		150		

9-3. AC Characteristics

Symbol	Parameter	Test Conditions		Min	Typ.	Max	Unit
		VDD	Conditions				
f _{sys1}	System Clock	5V	LP Crystal mode	32		200	Khz
		3V		32		200	
f _{sys2}	System Clock	5V	NT Crystal mode	0.2		10	Mhz
		3V		0.2		10	
f _{sys3}	System Clock	5V	HS Crystal mode	10		20	Mhz
		3V					
f _{sys4}	System Clock	5V	RC mode			6	Mhz
		3V				6	
T _{wdt}	Watchdog Timer	5V			20		mS
		3V			25		
T _{rht}	Reset Hold Time	5V			20		mS
		3V			25		

9-4. External RC Tables

RC 頻率表(5V, 25°C), Sample S1~S6

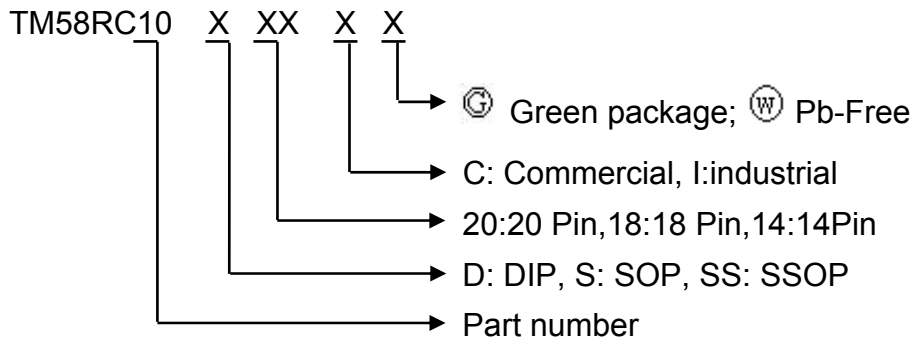
R	C	S1	S2	S3	S4	S5	S6	Freq(unit)
7.5M	0.1u	24.37	25.59	27.38	26.00	27.35	25.82	K Hz
	20p	25.10	26.08	27.61	26.48	27.54	26.33	
	PS(1)	25.21	26.25	27.88	26.64	27.67	26.43	
6M	0.1u	30.39	31.96	34.10	32.76	34.07	32.30	
	20p	31.40	32.66	34.38	33.07	34.33	32.96	
	--	31.63	32.88	34.81	33.36	34.58	33.17	
330K	0.1u	395.4	402.1	407.3	405.2	408.0	406.3	
	20p	407.0	413.2	417.7	416.0	417.6	417.0	
	--	421.7	427.8	433.8	430.5	432.1	431.1	
300K	0.1u	449.7	456.8	463.6	460.4	463.6	461.2	
	20p	463.3	469.5	476.0	472.6	474.7	473.2	
	--	480.4	486.5	494.4	489.7	491.4	489.8	
150K	0.1u	0.878	0.886	0.902	0.892	0.896	0.892	M Hz
	20p	0.905	0.912	0.929	0.918	0.920	0.916	
	--	0.939	0.946	0.964	0.951	0.953	0.949	
120K	0.1u	1.125	1.134	1.153	1.141	1.144	1.139	
	20p	1.163	1.171	1.192	1.178	1.179	1.175	
	--	1.203	1.211	1.233	1.218	1.217	1.214	
75K	0.1u	1.808	1.818	1.847	1.829	1.826	1.823	
	20p	1.882	1.890	1.921	1.902	1.896	1.893	
	--	1.951	1.959	1.992	1.969	1.958	1.958	
68K	0.1u	2.004	2.013	2.044	2.025	2.021	2.018	
	20p	2.088	2.095	2.129	2.109	2.100	2.098	
	--	2.162	2.169	2.203	2.181	2.170	2.170	
39K	0.1u	3.551	3.559	3.608	3.581	3.556	3.559	
	20p	3.753	3.755	3.807	3.775	3.743	3.748	
	--	3.935	3.939	3.993	3.954	3.917	3.916	
36K	0.1u	3.865	3.868	3.921	3.891	3.864	3.867	
	20p	4.076	4.080	4.134	4.103	4.065	4.070	
	--	4.275	4.278	4.334	4.295	4.255	4.253	

VDD = 5V

R	C	S1	S2	S3	S4	S5	S6	Freq(unit)
20K	0.1u	7.323	7.313	7.399	7.349	7.270	7.281	M Hz
	20p	7.849	7.833	7.921	7.861	7.758	7.770	
	--	8.137	8.114	8.195	8.141	8.041	8.048	
18K	0.1u	8.185	8.169	8.260	8.208	8.112	8.125	
	20p	8.770	8.745	8.840	8.775	8.669	8.679	
	--	9.087	9.056	9.147	9.080	8.964	8.973	

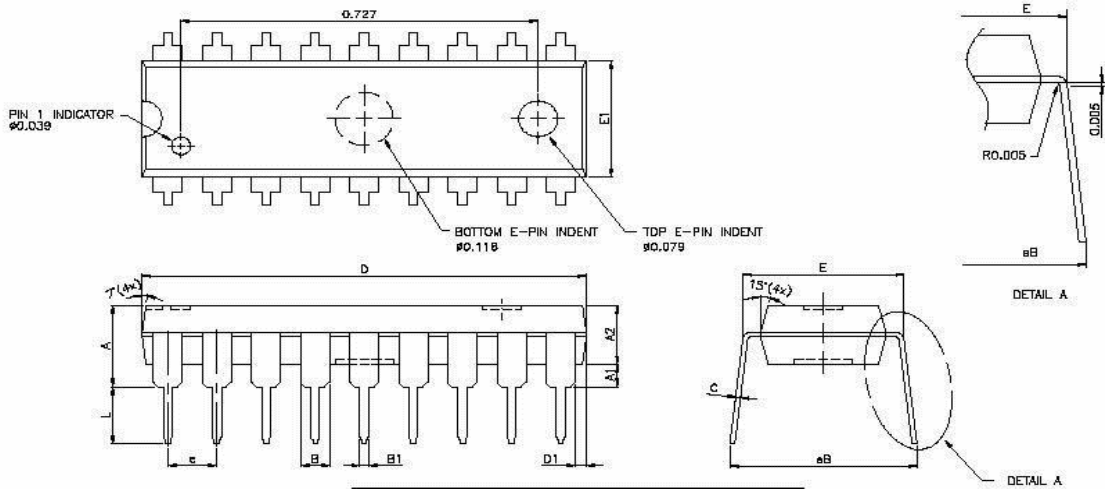
Note-1: No capacitor.

10. Part number Guide



10-1. Package mode

(1). 18Pin DIP (300 mil)



NOTES :

1. CONTROLLING DIMENSION : INCH
2. PACKAGE DIMENSION EXCLUDE MOLD FLASH OR PROTRUSION.
3. ALLOWABLE MOLD FLASH OR PROTRUSION SHALL NOT EXCEED 0.010".
4. FREMA MATERIAL: A194
5. TOLERANCE : 0.010" UNLESS OTHERWISE SPECIFIED.
6. AFTER SOLDER DIPPING LEAD THICKNESS WILL BE 0.020" MAX.
7. THE BOTTOM E-PIN ARE MARKED AS FOLLOW:

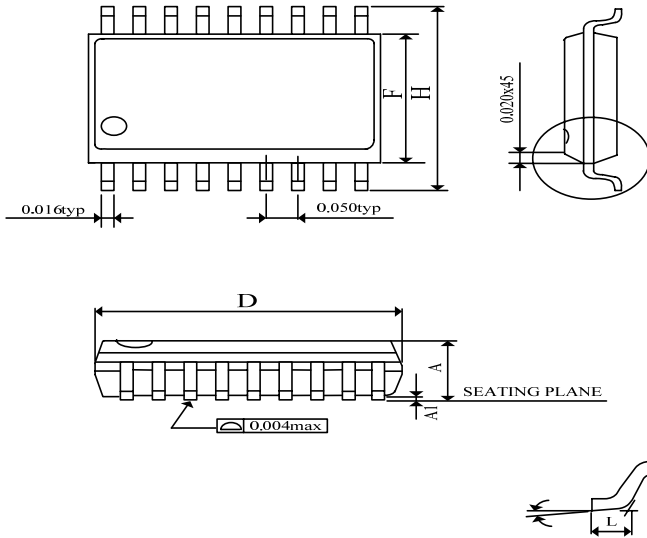


X : A~M (Except I)
Y : 0~9

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NDM	MAX	MIN	NDM	MAX
A	—	—	4.57	—	—	0.180
A1	0.38	—	—	0.015	—	—
A2	—	3.30	3.56	—	0.130	0.140
B1	0.36	0.46	0.56	0.014	0.018	0.022
B	1.27	1.52	1.78	0.050	0.060	0.070
C	0.20	0.25	0.33	0.008	0.010	0.013
D	22.71	22.98	23.11	0.894	0.904	0.910
D1	0.43	0.66	0.69	0.017	0.022	0.027
E	7.62	—	8.26	0.300	—	0.325
E1	6.40	6.50	6.65	0.252	0.256	0.262
e	—	2.54	—	—	0.100	—
L	3.18	—	—	0.125	—	—
eB	8.38	—	9.65	0.330	—	0.380

P-DIP 18PIN-300MIL

(2). 18Pin SOP (300 mil)

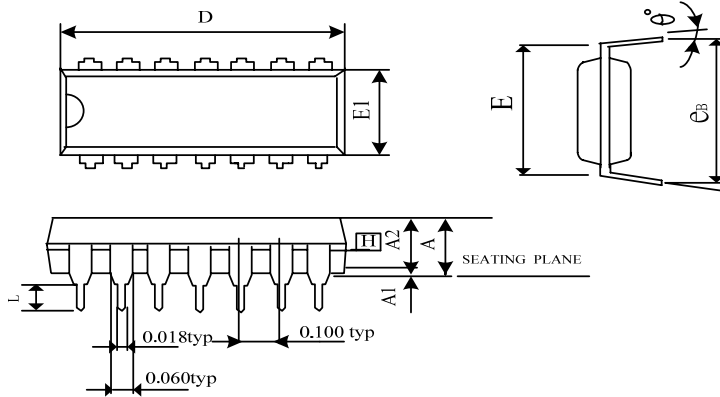


Symbol	MIN	MAX
A	0.093	0.104
A1	0.004	0.012
D	0.447	0.463
E	0.291	0.299
H	0.394	0.419
L	0.016	0.050
θ°	0	8

UNIT:INCH

- Note:
- 1.JEDEC OUTLINE:MS-013 AB
 - 2.DIMENSIONS "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.MOLD FLASH,PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .15mm(.006in) PER SIDE.
 - 3.DIMENSIONS "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .25mm(.010in) PER SIDE.

(3). 14Pin DIP (300 mil)



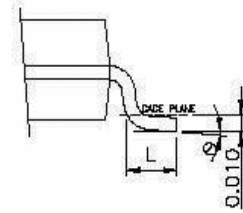
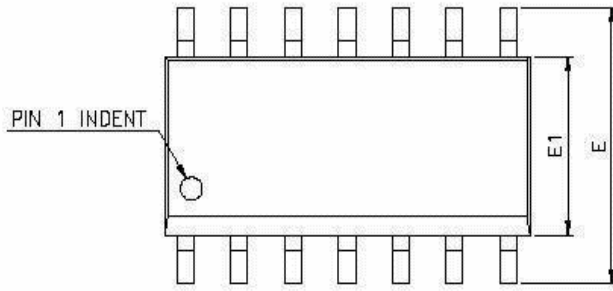
SYMBOLS	MIN	NOR	MAX
A	—	—	0.210
A1	0.015	—	—
A2	0.125	0.130	0.135
D	0.735	0.750	0.775
E	0.300 BSC		
E1	0.245	0.250	0.255
L	0.115	0.130	0.150
eB	0.335	0.355	0.375
θ°	0	7	15

UNIT : INCH

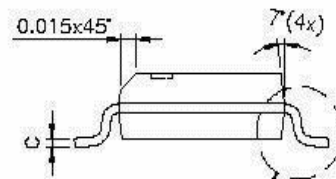
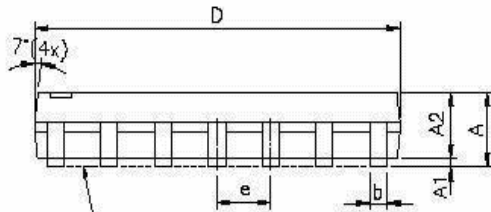
- NOTES:
- 1.JEDEC OUTLINE:MS-001 AA

- 3.eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- 4.POINTEO OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
- 5.DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
- 6.DATUM PLANE H COINCIDENT WITH THE BOTTOM OF LEAD,WHERE LEAD EXITS BODY.

(4). 14Pin SOP (150 mil)



DETAIL A



DETAIL A

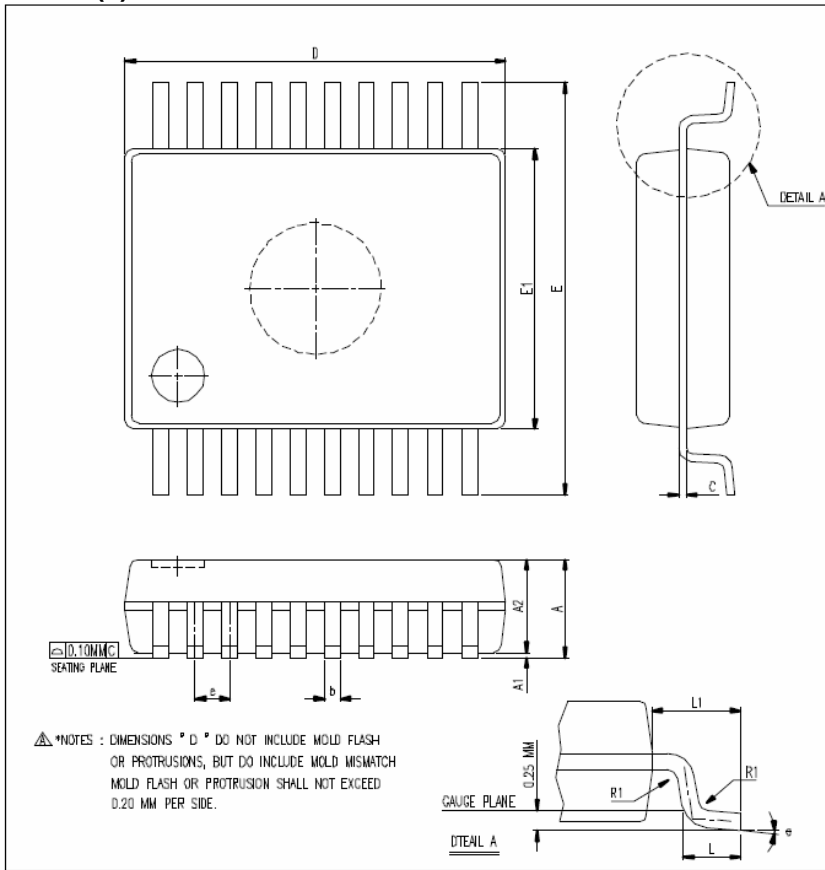
NOTE :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006 [0.15mm] PER END. DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010 [0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003 [0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028 [0.07mm]
5. TOLERANCE : ±0.010 [0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MS-012

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NDW	MAX	MIN	NDW	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	8.53	8.64	8.74	0.336	0.340	0.344
E	5.79	5.99	6.20	0.228	0.236	0.244
E1	3.81	3.91	3.99	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.38	0.71	1.27	0.015	0.028	0.050
y	—	—	0.076	—	—	0.003
⌀	⌀	—	⌀	⌀	—	⌀

SOP-14PIN-150MIL

(5). 20 PIN SSOP



△ NOTES : DIMENSIONS * D * DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH MOLD FLASH OR PROTRUSION SHALL NOT EXCEED 0.20 MM PER SIDE.

REV.	DESCRIPTION	BY	DATE
ORIG.	DRAWING ISSUE	SANDY CHEN	99.02.04
A.	ADD NOTES	SANDY CHEN	00.01.20

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A			2.0			0.079
A1	0.05			0.002		
A2	1.85	1.75	1.85	0.065	0.069	0.073
b	0.22	0.30	0.33	0.009	0.012	0.013
c	0.09	0.15	0.21	0.004	0.006	0.008
e	0.55 BASIC			0.026 BASIC		
D	6.90	7.20	7.50	0.272	0.283	0.295
E	7.40	7.80	8.20	0.291	0.307	0.323
E1	5.00	5.30	5.60	0.197	0.209	0.220
L	0.55	0.75	0.95	0.022	0.030	0.038
L1	1.25 REF.			0.049 REF.		
R1	0.09			0.004		
θ	D	4	8	0	4	8
WEDEC	MG-150 (AE)					

CWT Chant World Technology Inc.	□	ANGULAR	±
	XXXXXX ±0.005 XXXXXX ±0.005 XXXXXX ±0.005 XXXXXX ±0.2	ROUGHNESS	✓
TITLE	SSD PACKAGE OUTLINE 20L	SCALE	
	BODY WIDTH : 209 MIL		
DESIGNED	JASON CHANG 99.02.04	UNIT	QTY
CHECKED	C.C. CHO 00.01.20	FILE NAME	: P8F020P1
APPROVED	C.C. CHO 00.01.20	DWG. NO.:	CW-P8-001B